	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			under both	This docume level parts, t	ent is a declara he declaration	ation o 1 encor	of the substances mpasses all low	s within the er level ma	e manufactur terials for wl	er listed ite hich the ma	em. Note: if anufacturer	the item is an as has engineering	ssembly with low responsibility.	
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
upplie	r Information														
Company name* Company unique ID						Unique ID Authority Response Date*									
nsemi												2025-06-	08		
Contact N	ame		Title - Contact				Phone - Contact*					Email - Contact*			
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorize	d Representative*		Title - Representative				Phone - Representative*			Email - Representative*					
roduct-I	Env-Stewards		Product Envi	ro Compliance	npliance NA Product-Env-Stewards@onsemi					ards@onsemi.co	m				
	Requester Item Number Mfr Item		Number	ber Mfr Item Name			Effective Dat	te V	resion	Manufacturing Site		V	/eight*	UOM	Unit Type
		NVH820)S75L4SPB	Automotive 750 Module	V, 820A SSDC I	Power	2025-06-08			CNG		6	96191.9	mg	Each
Ianufa	cturing Proccess Informat	tion													
Terminal Plating / Grid Array Material			Terminal Base	Alloy	J-STD-020 MSI	L Rating	Peak Process Body Temperature Max Time a		ime at Peak	Temperatu	re Numb	er of Reflow Cyc	cles		
Matte Tin (Sn) - annealed CU Alloy				NA		0		С	30		second	s 3			
omments															
or more	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Case	82300.0	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		24690.002	mg
			Supplier	Poly(ButyleneTerephthalate)	30965-26-5		23044	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		2880.5	mg
			Supplier	PBT	26062-94-2		23044	mg
			-	Carbonic Dichloride	94334-64-2		8641.5	mg
Cover	26500.0	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		7950.0005	mg
			Supplier	Poly(ButyleneTerephthalate)	30965-26-5		7420	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		927.5	mg
			Supplier	PBT	26062-94-2		7420	mg
			-	Carbonic Dichloride	94334-64-2		2782.5	mg
DBC	46100.0	mg	Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		19223.6992	mg
			В	Nickel (Ni)	7440-02-0		92.2	mg
			Supplier	Copper (Cu)	7440-50-8		26784.0996	mg
Die	1.3	mg	Supplier	Silicon (Si)	7440-21-3		1.3	mg
Die Attach Solder	2000.0	mg	Supplier	Silver (Ag)	7440-22-4		80	mg
			Supplier	Tin (Sn)	7440-31-5		1910	mg
			Supplier	Misc.	Proprietary Data		10	mg
Glue	585.0	mg	Supplier	2,3-epoxypropyl-trimethoxysilan	2530-83-8		58.5	mg
			Supplier	Miscellaneous	Trade Secret		58.5	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		468	mg
Plating	65.0	mg	Supplier	Tin (Sn)	7440-31-5		32.5	mg
			В	Nickel (Ni)	7440-02-0		32.5	mg
Screw	2960.0	mg	Supplier	Sulfur (S)	7704-34-9		1.184	mg
			Supplier	Carbon (C)	7440-44-0		14.8	mg
			Supplier	Manganese (Mn)	7439-96-5		26.64	mg
			Supplier	Silicon (Si)	7440-21-3		14.8	mg
			Supplier	Iron (Fe)	7439-89-6		2901.3921	mg
			Supplier	Phosphorus (P)	7723-14-0		1.1838	mg
Silicone Gel	31360.0	mg	Supplier	Silicone	70900-21-9		2979.2	mg
		-	Supplier	Hexamethyldisilazane	68909-20-6		156.8	mg
			Supplier	Dimethyl Siloxane	68083-19-2		28224	mg
Solder preform	16700.0	mg	Supplier	Silver (Ag)	7440-22-4		534.4	mg

			Supplier	Tin (Sn)	7440-31-5	15130.1992	mg
			В	Antimony (Sb)	7440-36-0	918.5	mg
			Supplier	Copper (Cu)	7440-50-8	116.9	mg
Terminal	2500.0	mg	Supplier	Silicon (Si)	7440-21-3	6.75	mg
			В	Nickel (Ni)	7440-02-0	33.75	mg
			Supplier	Copper (Cu)	7440-50-8	2458.875	mg
			Supplier	Phosphorus (P)	7723-14-0	0.625	mg
Terminal Holder	485000.0	mg	Supplier	Silver (Ag)	7440-22-4	145.5	mg
			Supplier	Copper (Cu)	7440-50-8	484854.5	mg
Thermistor	120.0	mg	Supplier	Tin (Sn)	7440-31-5	1.5	mg
			Supplier	Nickel Oxide (NiO)	1313-99-1	0.18	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4	0.192	mg
			В	Nickel (Ni)	7440-02-0	28.02	mg
			Supplier	Gold (Au)	7440-57-5	0.024	mg
			Supplier	Iron (Fe)	7439-89-6	30	mg
			А	Lead Oxide (PbO)	1317-36-8	27.504	mg
			Supplier	Cobalt Oxide (Co3O4)	1308-06-1	0.18	mg
			Supplier	Manganese Tetraoxide (Mn3O4)	1317-35-7	0.18	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7	2.328	mg
			Supplier	Copper (Cu)	7440-50-8	13.26	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7	16.632	mg
Wire Bond - Al	0.6	mg	Supplier	Aluminum (Al)	7429-90-5	0.6	mg